

Appl. No. 10/709,427
Amdt. dated January 16, 2006
Reply to Office action of November 08, 2005

Amendments to the Claims:

This listing of claims will replace all prior versions and listings of claims in the application:

Listing of Claims:

- 5 1 (currently amended): A chip-packaging with bonding options having a plurality of package substrates, comprising:
- a first package substrate having a high voltage or a low voltage;
- a second package substrate having a high voltage or a low voltage, the voltage
- 10 level of the first package substrate being the logical opposite of the voltage
- level of the second package substrate; and
- a chip mounted on first package substrate, the chip comprising a plurality of the
- bonding option pads, one bonding pad being connected to the first package
- substrate, another bonding pad being connected to the second package
- substrate; and
- 15 a lead frame connected to one bonding pad.
- wherein each bonding option pad of the chip is selectively connected to the first
- package substrate or the second package substrate.
- 20 2 (cancelled).
- 3 (currently amended): The chip-packaging of the ~~claim 2~~ claim 1 wherein the high
- voltage is the voltage of the power supply and the low voltage is the ground voltage.
- 4 (currently amended): The chip-packaging of the claim 1. further comprising a plurality
- 25 of lead frames, wherein the each lead frame is connected to one pin of the
- chip-packaging.

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- 5 (original): The chip-packaging of the claim 4 wherein the pin is connected to a high voltage, a low voltage, or an input/output signal.
- 6 (original): The chip-packaging of the claim 1 wherein the first package substrate and the second package substrate have different voltages.
- 7 (original): The chip-packaging of the claim 1 wherein the first package substrate extends outside the chip and the second package substrate surrounds the chip.
- 10 8 (currently amended): The chip-packaging of the claim 1 wherein the first package substrate and the second package substrate substantially approximate each of a plurality of the bonding option pads.
- 9-18 (cancelled).
- 15 19 (new): The chip-packaging of the claim 4 wherein the pin is connected to an input/output signal.
- 20 20 (new): The chip-packaging of the claim 1 further comprising a plurality of lead frames, each bonding option pad of the chip having a corresponding lead frame, wherein each bonding option pad is selectively connected to the first package substrate, the second package substrate, or the corresponding lead frame.